

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S14	2	bond adj pad and solder adj bump and polyimide with benzocyclobutene with stack	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:01
S15	2	bond adj pad and polyimide with benzocyclobutene with stack	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:02
S16	8	polyimide with benzocyclobutene with stack	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:03
S17	1	bond adj pad and polyimide with bcb with stack	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:02
S18	16	polyimide with benzocyclobutene with stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:03
S19	51	polyimide with benzocyclobutene same stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:12
S20	29	polyimide with benzocyclobutene same stack\$3 and (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:14
S22	22	polyimide with benzocyclobutene same stack\$3 not (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:13
S23	29	polyimide with bcb same stack\$3 and (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:14

S24	50	polyimide with (bcb or benzocyclobutene) same stack\$3 and (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:15
S25	1440	polyimide with bcb not benzocyclobutene same stack\$3 and (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:15
S26	29	polyimide with bcb same stack\$3 and (bond or bump or pad or solder or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:15
S27	17	polyimide with bcb same stack\$3 and (bond or bump or pad or solder or ball) not benzocyclobutene	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 21:15